

PNA1605F (PN116)

Silicon planar type

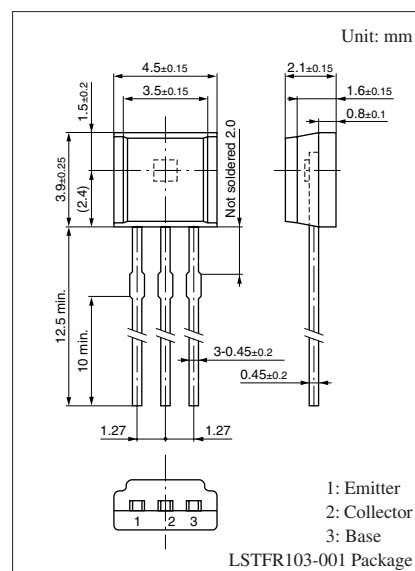
For optical control systems

■ Features

- High sensitivity
- Wide directivity characteristics, suited for detecting GaAs LEDs:
 $\theta = 70^\circ$ (typ.)
- Fast response: $t_r, t_f = 8 \mu s$ (typ.)
- Side-view type package

■ Absolute Maximum Ratings $T_a = 25^\circ C$

Parameter	Symbol	Rating	Unit
Collector-emitter voltage (Base open)	V_{CEO}	20	V
Collector-base voltage (Emitter open)	V_{CBO}	30	V
Emitter-collector voltage (Base open)	V_{ECO}	5	V
Emitter-base voltage (Collector open)	V_{EBO}	5	V
Collector current	I_C	10	mA
Collector power dissipation	P_C	100	mW
Operating ambient temperature	T_{opr}	-25 to +85	$^\circ C$
Storage temperature	T_{stg}	-30 to +100	$^\circ C$



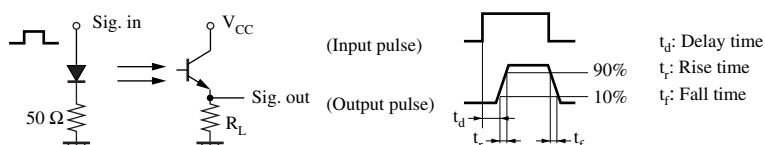
■ Electrical-Optical Characteristics $T_a = 25^\circ C \pm 3^\circ C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Photocurrent *1	$I_{CE(L)}$	$V_{CE} = 10 V, L = 100 lx$	0.2	0.8		mA
Dark current	I_{CEO}	$V_{CE} = 10 V$		0.05	2.00	μA
Peak emission wavelength	λ_p	$V_{CE} = 10 V$		900		nm
Half-power angle	θ	The angle from which photocurrent becomes 50%		70		$^\circ$
Rise time *2	t_r	$V_{CC} = 10 V, I_{CE(L)} = 1 mA, R_L = 100 \Omega$		8		μs
Fall time *2	t_f			9		μs
Collector-emitter saturation voltage *1	$V_{CE(sat)}$	$I_{CE(L)} = 1 mA, L = 1000 lx$		0.3	0.6	V

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

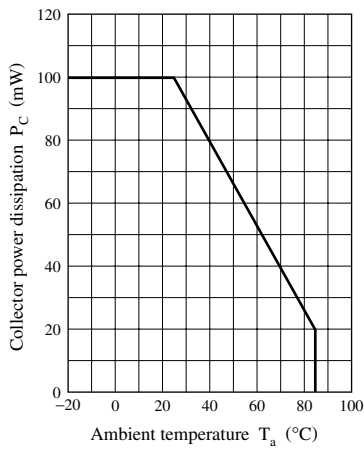
2. *1: Source: Tungsten (color temperature 2856 K)

*2: Switching time measurement circuit

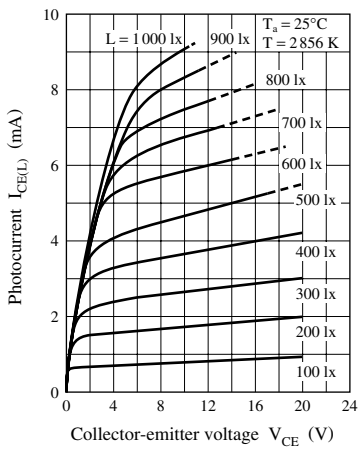


Note) The part number in the parenthesis shows conventional part number.

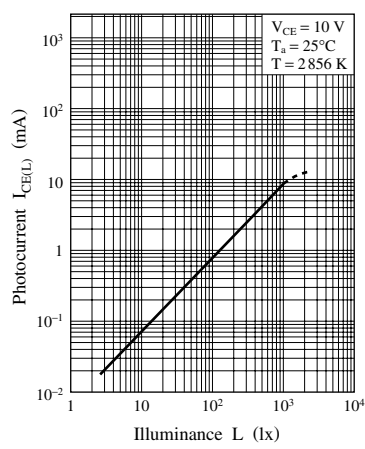
$P_C - T_a$



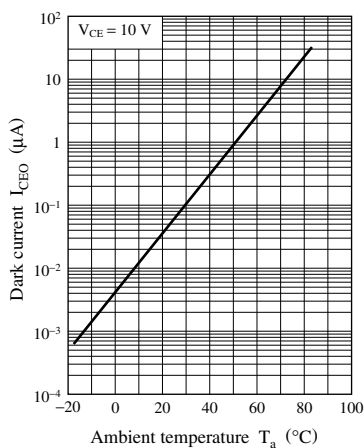
$I_{CE(L)} - V_{CE}$



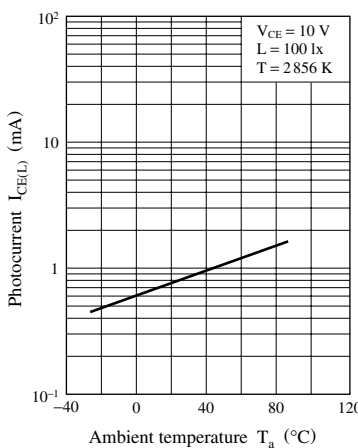
$I_{CE(L)} - L$



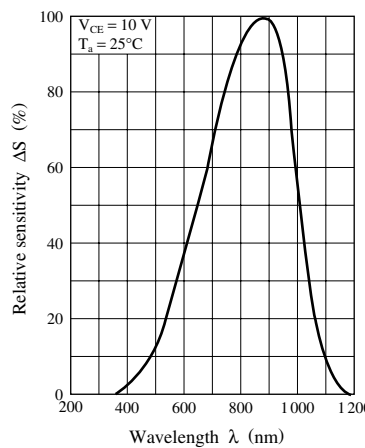
$I_{CEO} - T_a$



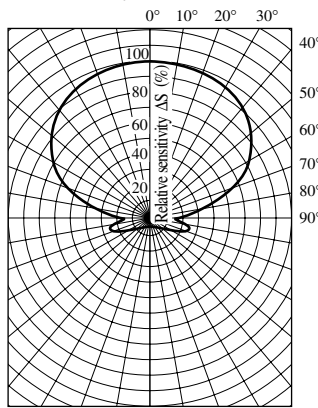
$I_{CE(L)} - T_a$



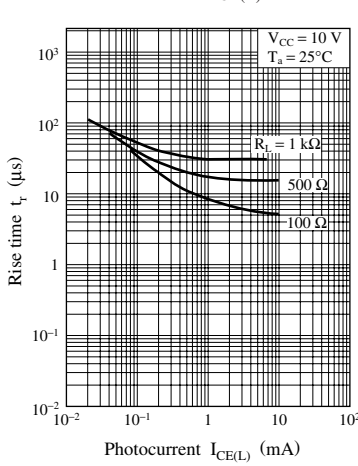
Spectral sensitivity characteristics



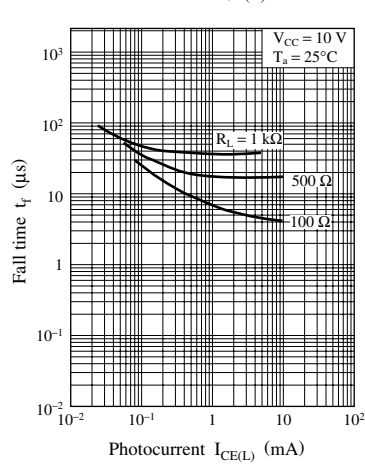
Directivity characteristics



$t_r - I_{CE(L)}$



$t_f - I_{CE(L)}$



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